

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3927419

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HIDEAKI NISHIUCHI	03/31/2016
FUTARO EBINA	04/04/2016
SATOSHI TOTAKE	04/01/2016
TAKUYA NOMURA	04/12/2016
KUNIO MORIYAMA	04/05/2016
RECEIVING PARTY DATA	
Name:	HITACHI, LTD.
Street Address:	6-6, MARUNOUCHI 1-CHOME, CHIYODA-KU,
City:	TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15106876
CORRESPONDENCE DATA	
Fax Number:	(703)684-1157
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	703-684-1120
Email:	svannarath@mmpiaw.com
Correspondent Name:	MATTINGLY & MALUR, PC
Address Line 1:	1800 DIAGONAL ROAD
Address Line 2:	SUITE 210
Address Line 4:	ALEXANDRIA, VIRGINIA 22314
ATTORNEY DOCKET NUMBER:	H-10457
NAME OF SUBMITTER:	SHRINATH MALUR
SIGNATURE:	/Shrinath Malur/
DATE SIGNED:	06/21/2016
Total Attachments: 5	
source=10457-ASN#page1.tif	
source=10457-ASN#page2.tif	

source=10457-ASN#page3.tif

source=10457-ASN#page4.tif

source=10457-ASN#page5.tif

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CHARGED PARTICLE BEAM SYSTEM, SYMCHROTRON, AND BEAM EJECTION METHOD THEREFOR

Invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) <u>Hideaki Nishiuchi</u> Hideaki NISHIUCHI	<u>3 / 31 / 2016</u>
2) _____ Futatarou EBINA	_____
3) _____ Satoshi TOOFAKE	_____
4) _____ Takuya NOMURA	_____
5) _____ Kunio MORIYAMA	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd.,

a corporation organized under the laws of Japan,

located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan

receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd.,

its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CHARGED PARTICLE BEAM SYSTEM, SYMCHROTRON, AND BEAM EJECTION METHOD THEREFOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi, Ltd.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated beside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	_____ Hideaki NISHIUCHI	_____
2)	Futaro EBINA _____ Futaro EBINA	4/4/2016
3)	_____ Satoshi TOTAKE	_____
4)	_____ Takuya NOMURA	_____
5)	_____ Kunio MORIYAMA	_____
6)	_____	_____
7)	_____	_____
8)	_____	_____
9)	_____	_____
10)	_____	_____

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 8-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to CHARGED PARTICLE BEAM SYSTEM, SYMCHROTRON, AND BEAM EJECTION METHOD THEREFOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

	INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1)	Hideaki NISHIUCHI	
2)	Fumitarou EBINA	
3)	Satoshi Totake Satoshi TOTAKE	04/01/2016
4)	Takuya NOMURA	
5)	Kunio MORIYAMA	
6)		
7)		
8)		
9)		
10)		

ASSIGNMENT
(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 8-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CHARGED PARTICLE BEAM SYSTEM, SYMCHROTRON, AND BEAM EJECTION METHOD THEREFOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ Hideaki NISHIUCHI	_____
2) _____ Futarou EBINA	_____
3) _____ Satoshi TOOTAKE	_____
4) <u>Takuya Nomura</u> _____ Takuya NOMURA	<u>4/12/2016</u> _____
5) _____ Kunio MORIYAMA	_____
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

ASSIGNMENT
(讓渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me by Hitachi, Ltd., a corporation organized under the laws of Japan, located at 6-6, Marunouchi 1-chome, Chiyoda-ku, Tokyo, Japan receipt of which is hereby acknowledged I do hereby sell and assign to said Hitachi, Ltd., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

CHARGED PARTICLE BEAM SYSTEM, SYMCHROTRON, AND BEAM EJECTION METHOD THEREFOR

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said Hitachi, Ltd., its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said Hitachi, Ltd.,

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)	Date Signed (署名日)
1) _____ Hideaki NISHIUCHI	_____
2) _____ Futaro EBINA	_____
3) _____ Satoshi TOTAKE	_____
4) _____ Takuya NOMURA	_____
5) <u>Kunio Moriyama</u> _____ Kunio MORIYAMA	<u>4/5/2016</u>
6) _____	_____
7) _____	_____
8) _____	_____
9) _____	_____
10) _____	_____

PATENT